

11. A peripheral device PCB package comprising:
two stamped metal covers each having a first side and a second side having an edge extending from one of said sides of each cover; and
a plastic frame element associated with each of the covers wherein the plastic frame elements are injection molded to secure the edge of each cover to the plastic frame element.
12. The package as claimed in Claim 11 further comprising:
a plastic perimeter surface extending beyond a plane of the metal cover to facilitate bonding of the two covers.
13. The package as claimed in Claim 12 wherein each of the plastic perimeter surfaces is integrally formed with the plastic frame elements.
14. The package as claimed in Claim 12 wherein the plastic perimeter surface is an energy director.
15. The package as claimed in Claim 11 wherein a finger extends from one of said sides.
16. The package as claimed in Claim 11 wherein a plurality of fingers extend from at least two sides.
17. The package as claimed in Claim 11 wherein the edge of the metal cover is bent to conform to the shape of the plastic frame element.
18. A PCB package comprising:
a first package half including a stamped metal cover having an edge formed in a U-shape and a frame element injection molded within the U-shaped edge of the metal cover;
a second package half including a stamped metal cover and a molded frame element attached to the metal cover; and
the first package half sonically bonded to the second package half.
19. The package as claimed in Claim 18 wherein the first package half includes a plane bisecting the U-shaped edge at its terminal portion on a first side and a second side of the first

package half and a plastic perimeter surface exposed and extending beyond the plane of the first package half to facilitate bonding with the second package half.

20. The package as claimed in Claim 19 wherein the plastic perimeter surface is an energy director.

21. The package as claimed in Claim 18 wherein the second package half includes a plane bisecting the U-shaped edge at its terminal portion on a first and a second side of the second package half and a plastic perimeter surface exposed and recessed below the plane of the second package half to facilitate bonding with the first package half.

22. The package as claimed in Claim 18 wherein the edge is secured to the frame element and the frame element is injection molded partially around the edge.

23. The package as claimed in Claim 18 wherein a finger extends at an angle from the edge of the metal cover and the finger having the frame element partially injection molded around the finger.